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| --- | --- | --- |
|  | **Famos** | **Mitikas** |
| **No. of die** | 1 | 2 |
| **No. of layers in the substrate** | 11 | 11 |
| **Package ball count** | 896 | 1296 |
| **Flip-chip or wirebond?** | Flip-chip | Wirebond |
| **Pad or bump count (total if multiple die)** | 13116 | 11264 |
| **Count of D2D signals** | NA |  |
| **Number of power planes** | 6 | 6 |
| **Layer(s) used for power planes (add another worksheet to this spreadsheet to capture details if you like)** | L03, L05, L06, L07, L08, L09 | L03, L05, L06, L07, L08, L09 |
| **Maximum length of D2D signal trace** | NA |  |
| **Minimum length of D2D signal trace** | NA |  |
| **Identification of differential pairs: look at signal names and list examples if you find any** | CK0, CK1, CK2, CK3, CK4, DQS0, DQS1, DQS2, DQS3, DQS4, DQS5, DQS6, DQS7, DQS8, PECLK, PE0R, PE0T, PE1R, PE1T, PE2R, PE2T, PE3R, PE3T, PE4R, PE4T, PE5R, PE5T, PE6R, PE6T, PE7R, PE7T, X1CLK, X2CLK, X10R, X10T, X11R, X11T, X12R, X12T, X13R, X13T, X20R, X20T, X21R, X21T, X22R, X22T, X23R, X23T | CCLK, CLK\_A, C0CLK, C1CLK, D0CLK, D1CLK, D2CLK, OCLK\_0, OCLK\_1, OCLK\_2, OCLK0, 01CLK, RCLK\_0, RCLK\_1, R0CLK, R1CLK, 2OCLK |
| **No. of die** | 1 | 2 |
|  |  |  |